TFT DISPLAY SPECIFICATION



WINSTAR Display Co.,Ltd. 華凌光電股份有限公司





WEB: https://www.winstar.com.tw E-mail: sales@winstar.com.tw

SPECIFICATION

CUSTOMER :	
MODULE NO.:	WF0200BSYAJDNNO#
	1
APPROVED BY:	CRIM
(FOR CUSTOMER USE ONLY	PCB VERSION: DATA:

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY
			周园园
ISSUED DATE:	2022/06/30		

TFT Display Inspection Specification: https://www.winstar.com.tw/technology/download.html Precaution in use of TFT module: https://www.winstar.com.tw/technology/download/declaration.html



MODLE NO:

RECORDS OF REVISION			DOC. FIRST ISSUE
VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2022/05/13		First issue
A	2022/06/08		Correct Summary
В	2022/06/30		Correct LCD type

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1.Module Classification Information

S J N 0 W F 0200 B Y D N # A (1) 7 (11) 2 3 4 (5) 6 8 9 10 12 13)

①	Brand: WINSTAR DISPLAY CORPORATION												
2	Display Type: F→TFT Type, J→Custom TFT												
3	Display Size : 2.0" TFT												
4	Model serials no.											A	
(5)	Backlight	F→CCFL, W	hite				T	\rightarrow L	ED, White	e			•
9	Type:	S→LED, Hig	h Lig	ht Wh	ite		Z	→N	ichia LED), W	hite		
	LCD Polarize	A→Transmis	sive,	N.T, IF	PS T	FT	Q	\rightarrow T	ransmissi	ve, S	uper W.T,	12:00)
	Type/	C→Transmis	sive,	N. T, 6	:00 ;		R	→ T	ransmissiv	ve, S	uper W.T,	O-TF	Т
	Temperature	F→Transmiss	sive, l	N.T,12	:00;		V	\rightarrow T	ransmissi	ve, S	uper W.T,	VA T	FT
6	range/ Gray	I→Transmiss					W	/ →]	Transmissi	ve,	Super W.T,	IPS 7	ΓFT
	Scale Inversion	K→Transflec	tive,	W.T,12	2:00						V.T, VA TF		
	Direction	L→Transmis	sive,	W.T,12	00:		Y	\rightarrow T	ransmissi	ve, V	V.T, IPS TI	T	
	Birection	N→Transmis	sive,	Super	W.T,	6:00		$\overline{}$			V.T, O-TFT		
	A: TFT LCD										L BOAR	D	
	B: TFT+SCREV				_	D			FT+ SCR				
7	C: TFT+ SCRE								FT+D/V				
	D: TFT+ SCREW	HOLES +A/D B	OARD	+CONT	ROL	BOA	RD I	: TF	T+ SCRE	EW I	HOLES +D	/V B	OARD
	E: TFT+ SCREV	W HOLES +PO	OWE	R BC	OAR	Ď	J	: TI	FT+POWI	ER E	BD		
	Resolution:				,					1			
	A 128160 B			0240	D		234	Е	480272	F	640480		
8	G 800480 H			0480	J	240	320	K	800600	L	240400		
	M 1024768 N	128128 F	128	80800	Q	480	800	R	640320	S	480128		
	T 800320 U	8001280 V	17	6220	W	128	0398	X	1024250	Y	1920720		
	Z 800200 2	1024324 3	720	01280	4	1920	1200	5	1366768	6	1280320		
9	D: Digital L:	LVDS M:M	IPI										
	Interface:	/											
10	N Without co	ntrol board	A	8Bit		В		16E	Bit	Н	HDMI		
	I I2C Interfa	ce	R	RS232	2	S	SPI	Inte	erface	U	USB		
	TS:												
	N Without TS		T	Resist	ive t	ouch	panel	1	C Capaci	itive	touch pane	el (G-	F-F)
11)	G Capacitive to	ouch panel (G-	G)			C 1	Ca	apac	itive touch	ı par	nel (G-F-F)	+OC	A
	C2 Capacitive to	ouch panel (G-	F-F)-	-OCR		G	Ca	apac	itive touch	n pai	nel (G-G)+	OCA	
	G2 Capacitive to	ouch panel (G-	G)+C	OCR		В	C	ΓP+0	GG+USB				
12	Version: X:Rasj	pberry pi											
13	Special Code	#:Fit in wit	th RO	HS dir	ectiv	ve reg	gulatio	ons					
		1											

2.Summary

TFT 2.0" is a IPS transmissive type color active matrix TFT liquid crystal display that use amorphous silicon TFT as switching devices. This module is a composed of a TFT_LCD module, It is usually designed for industrial application and this module follows RoHs.



WF0200BSYAJDNN0#

3.General Specifications

Item	Dimension	Unit
Size	2.0"	inch
Dot Matrix	240 x RGB x 320(TFT)	dots
Module dimension	38.8(W) x 52.3(H) x 2.15(D)	mm
Active area	30.60 x 40.80	mm
Pixel Pitch	0.1275 x 0.1275	mm
LCD type	TFT, Normally Black, Transmissive	•
TFT Interface	MCU / SPI	
TFT Driver IC	ST7789VI or Equivalent	
Viewing angle	80/80/80/80	
Aspect Ratio	3:4	
Backlight Type	LED,Normally White	
With /Without TP	Without TP	
Surface	Glare	

^{*}Color tone slight changed by temperature and driving voltage.

4.Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	TOP	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	TST	-30	_	+80	$^{\circ}\!\mathbb{C}$

Note: Device is subject to be damaged permanently if stresses beyond those absolute maximum ratings listed above

1. Temp. $\leq\!60^{\circ}\!\!\!\mathrm{C}$, 90% RH MAX. Temp. $>\!60^{\circ}\!\!\mathrm{C}$, Absolute humidity shall be less than 90% RH at $60^{\circ}\!\!\mathrm{C}$

5.Electrical Characteristics

5.1. Operating conditions

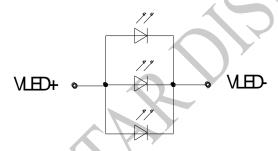
Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Analog	V_{DD}	_	2.4	3.3	3.6	V
Interface Operation Voltage	V _{DDI}	_	1.65	1.8	3.6	V
Supply Current For LCM	I _{DD}	V _{DD} = V _{DDI} = V _{CC} =3.0V	_	6.0	9.0	mA

Note: to avoid power supply noise, please avoid using driving conditions close to min, or max value

5.2. LED driving conditions

Parameter	Symbol	Min.	Тур.	Max.	Unit	Remark
LED current	_	_	60		mA	_
LED voltage	VLED+	5.5	6.0	6.5	V	Note 1
LED Life Time	_		50,000	_	Hr	Note 2,3,4

Note 1: There are 1 Groups LED



Back Light Circuit

Note 2 : Ta = 25 °C

Note 3: Brightness to be decreased to 50% of the initial value

Note 4: The single LED lamp case

6.DC CHARATERISTICS

Parameter	Symbol		Rating	Unit	Condition	
1 ar anicter			Max	Omt	Condition	
Low level input voltage	VIL	0	-	0.3VCC	V	
High level input voltage	V _{IH}	0.7VCC	-	VCC	V	<u> </u>

7.AC Characteristics

7.1. 8080 Series MCU Parallel Interface Characteristics: 18/16/9/8-bit Bus

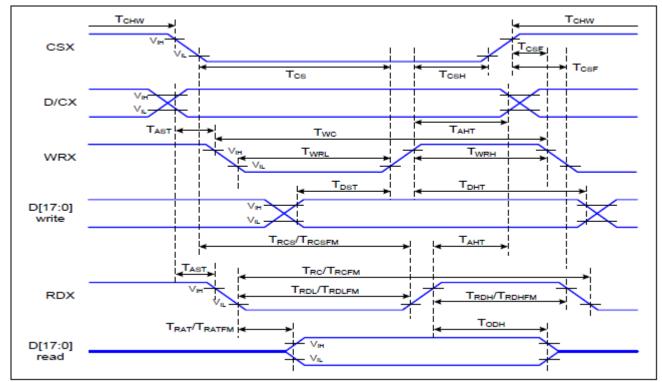


Figure 1Parallel Interface Timing Characteristics (8080-Series MCU Interface)

VDDI=1.65 to 3.6V, VDD=2.4 to 3.6V, GND=0V, Ta= 25 $\,^{\circ}$ C

Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	TAST	Address setup time	0		ns	
D/CX	TAHT	Address hold time (Write/Read)	10		ns	-
CSX	TCHW	Chip select "H" pulse width	0		ns	_
00%	TCS	Chip select setup time (Write)	15		ns	A
	TRCS	Chip select setup time (Read ID)	45		ns	~ C.
	TRCSFM	Chip select setup time (Read FM)	355		ns	
	TCSF	Chip select wait time (Write/Read)	10		ns	
	TCSH	Chip select hold time	10		ns	<i>y</i>
WRX	TWC	Write cycle	66	~ 〔	ns	
	TWRH	Control pulse "H" duration	15		ns	
	TWRL	Control pulse "L" duration	15		ns	
RDX (ID)	TRC	Read cycle (ID)	160	,	ns	When read ID data
	TRDH	Control pulse "H" duration (ID)	90		ns	
	TRDL	Control pulse "L" duration (ID)	45		ns	
RDX	TRCFM	Read cycle (FM)	450		ns	When read from
	TRDHFM	Control pulse "H" duration (FM)	90		ns	
(FM)	TRDLFM	Control pulse "L" duration (FM)	355		ns	frame memory
D[17:0]	TDST	Data setup time	10		ns	For CL=30pF
	Трнт	Data hold time	10		ns	
	T _{RAT}	Read access time (ID)		40	ns	
	T _{RATFM}	Read access time (FM)		340	ns	
	Торн	Output disable time	20	80	ns	

Table 8080 Parallel Interface Characteristics

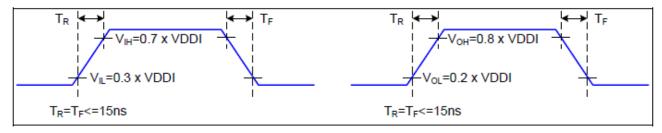


Figure 2 Rising and Falling Timing for I/O Signal

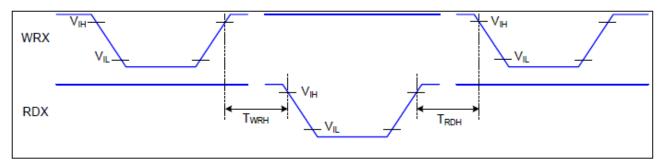


Figure 3 Write-to-Read and Read-to-Write Timing

Note: The rising time and falling time (Tr, Tf) of input signal and fall time are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

7.2. 3-line Serial Interface

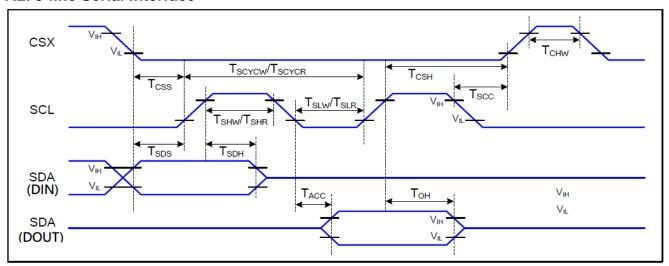


Figure 4 3-line serial Interface Timing Characteristics

VDDI=1.65 to 3.6V, VDD=2.4 to 3.6V, GND=0V, Ta= 25 $\,^{\circ}$ C

Signal	Symbol	Parameter	Min	Max	Unit	Description
	T _{CSS}	Chip select setup time (write)			ns	
	Тсѕн	Chip select hold time (write)	15		ns	
CSX	T _{CSS}	Chip select setup time (read)	60		ns	
	Tscc	Chip select hold time (read)	65		ns	
	Тснw	Chip select "H" pulse width	40		ns	
	Tscycw	Serial clock cycle (Write)	16		ns	
	T _{SHW}	SCL "H" pulse width (Write)	7		ns	
801	Tstw	SCL "L" pulse width (Write)	7		ns	
SCL	Tscycr	Serial clock cycle (Read)	150		ns	
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA	T _{SDS}	Data setup time	7		ns	
(DIN)	T _{SDH}	Data hold time	7		ns	
SDA	Tacc	Access time	10	50	ns	For maximum CL=30pF
(DOUT)	Тон	Output disable time	15	50	ns	For minimum CL=8pF

Table 3-line serial Interface Characteristics

7.3. Reset Timing:

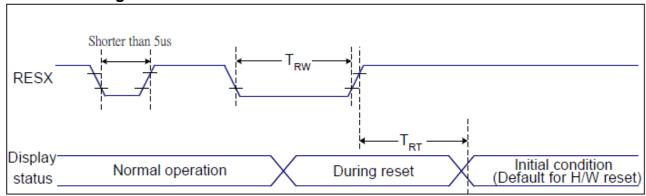


Figure 5 Reset Timing

VDDI=1.65 to 3.6V, VDD=2.4 to 3.6V, GND=0V, Ta=25 °C

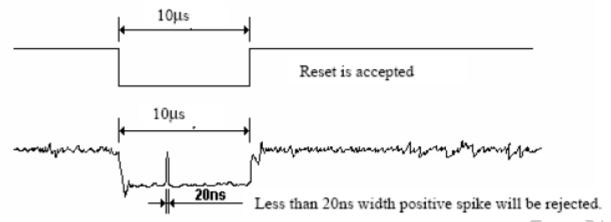
Related Pins	Symbol	Parameter	MIN	MAX	Unit
	TRW	Reset pulse duration	10	-	us
RESX		Deset sensel	-	5 (Note 1, 5)	ms
	TRT	Reset cancel		120 (Note 1, 6, 7)	ms

Notes:

- 1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.
- 2. Spike due to an electrostatic discharge on RESXline does not cause irregular system reset according to the table below:

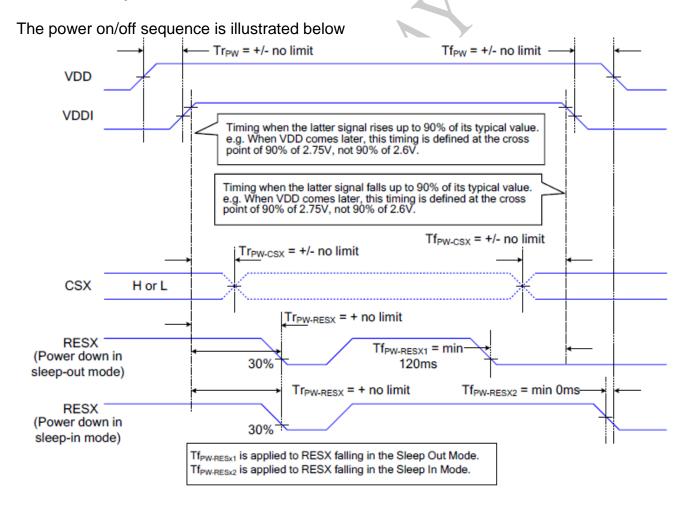
RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

- 3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.
- 4. Spike Rejection also applies during a valid reset pulse as shown below:



- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.
- 7. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

7.4. Power sequences



8.Optical Characteristics

Item		Symbol	Condition.	Min	Тур.	Max.	Unit	Remark
Response tim	ie	Tr+ Tf	θ=0°、Φ=0°	-	35	45	ms	Note 3
Contrast ratio)	CR	At optimized viewing angle	640	800	-	-	Note 4
Color	White	Wx	θ=0°、Φ=0	0.246	0.296	0.346		Note
Chromaticity	vvriite	Wy	θ =0 \wedge Φ =0	0.275	0.325	0.375	^	2,6,7
Viewing angle	Hor.	ΘR	CR≧ 10	-	80	-	K	
Viewing angle (Gray Scale	HOI.	ΘL		-	80	-	Deg.	Note 1
Inversion	Ver.	ΦТ		-	80	-		
Direction)		ΦВ		-	80	(
Brightness		ı	-	850	950		cd/m ²	Center of display
Uniformity		(U)	-	75	-	-	%	Note5

Ta=25±2°C

Note 1: Definition of viewing angle range

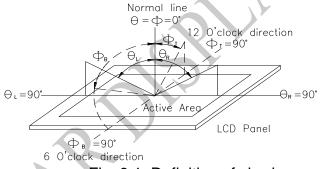


Fig. 8.1. Definition of viewing angle

Note 2: Test equipment setup:

After stabilizing and leaving the panel alone at a driven temperature for 10 minutes, the measurement should be executed. Measurement should be executed in a stable, windless, and dark room. Optical specifications are measured by Topcon BM-7 or BM-5 luminance meter 1.0° field of view at a distance of 50cm and normal direction.

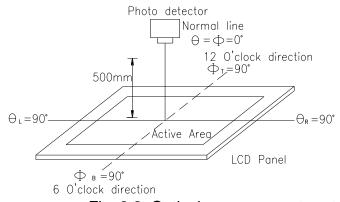
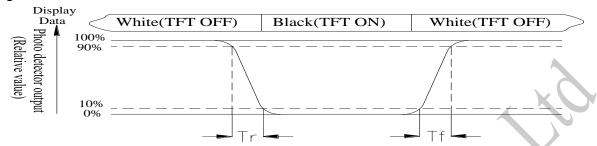


Fig. 8.2. Optical measurement system setup

Note 3: Definition of Response time:

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time, Tr, is the time between photo detector output intensity changed from 90%to 10%. And fall time, Tf, is the time between photo detector output intensity changed from 10%to 90%



Note 4: Definition of contrast ratio:

The contrast ratio is defined as the following expression.

Note 5: Definition of Luminance Uniformity

Active area is divided into 9 measuring areas (reference the picture in below). Every measuring point is placed at the center of each measuring area.

Luminance Uniformity (U) = Lmin/Lmax x100%

L = Active area length

W = Active area width

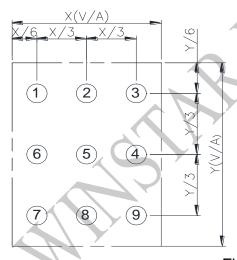


Fig 8.3. Definition of uniformity

Note 6: Definition of color chromaticity (CIE 1931) Color coordinates measured at the center point of LCD

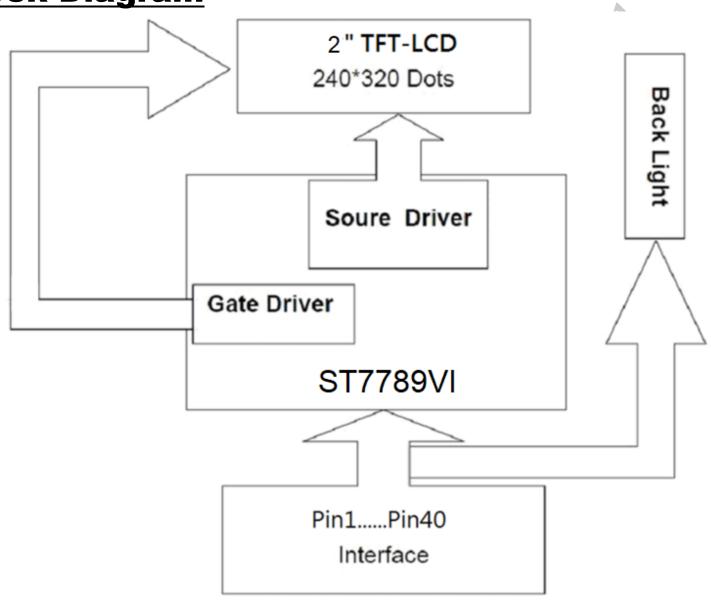
Note 7: Measured at the center area of the panel when all the input terminals of LCD panel are electrically opened.

9.Interface 9.1. LCM PIN Definition

	PIN Definition	•					
NO	Symbol	Function					
1	GND	Ground					
2	NC	No connection					
3	NC	No connection					
4	NC	No co	No connection				
5	NC	No co	nnect	ion			, KO'
6	NC	No co	nnect	ion		/	
7	VDD	Powe	r supp	oly			
8	VDDI			-	I/O System.		
9	TE	writin	g.		nal is used to synchi e let this pin open	ronize MCU	to frame memory
10	CSX	Low e	Chip selection pin Low enable. High disable.				
11	DCX(SCL)	(D/CX): This pin is used to select "Data or Command" in the parallel interface. DCX='1': display data or parameter. DCX='0': command data, (SCL): When SPI mode, This pin is used to be serial interface clock.					
12	WRX(D/CX)	Display data/command selection Second Data lane in 2 data lane serial interface. (WRX): Write enable in MCU parallel interface. (D/CX): When 4-SPI mode, This pin in 4-line serial interface If not used, please fix this pin at VDDI or GND.					
13	RDX	-Read enable in 8080 MCU parallel interfaceIf not used, please fix this pin at VDDI or GND.					
14~29	DB0~DB15	Data bus line					
30	RESX	System reset pin. signal is active low					
31	IMO	The MCU interface mode select.					
32	IM1	IM2	IM1	IM0	MPU Interface Mode	Data pin	
		0	0	0	80-8bit parallel I/F	DB[7:0]	
	IM2	0	0	1	80-16bit parallel I/F	DB[15:0]	
		0	1	0	80-9bit parallel I/F	DB[8:0]	
33		0	1	1	80-18bit parallel I/F	DB[17:0],	
		1	0	1	3-line 9bit serial I/F	SDA: in/out	
				0	4-line 8bit serial I/F	SDA: in/out	

34~35	DB16~DB17	Data bus line	
36	VLED-	Cathode of LED backlight.	
37	VLED-	Cathode of LED backlight.	
38	VLED+	Anode of LED backlight.	
39	NC(SDA)	When SPI mode, This pin is SPI interface input/output pin. The data is latched on the rising edge of the SCL signal. If not used(NC), please fix this pin at VDDI or GND level.	
40	NC	No connection	

10.Block Diagram



11.Reliability

Content of Reliability Test (Wide temperature, -20°C ~70°C)

Environmental Test				
Test Item	Content of Test	Test Condition	Note	
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°ℂ 200hrs	2	
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°ℂ 200hrs	1,2	
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70℃ 200hrs		
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20℃ 200hrs	1	
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max	60℃,90%RH 96hrs	1,2	
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20°ℂ/70°ℂ 10 cycles		
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3	
Static electricity test	Endurance test applying the electric stress to the finished product housing.	Contact±4KV Air±8KV 10 times	4	

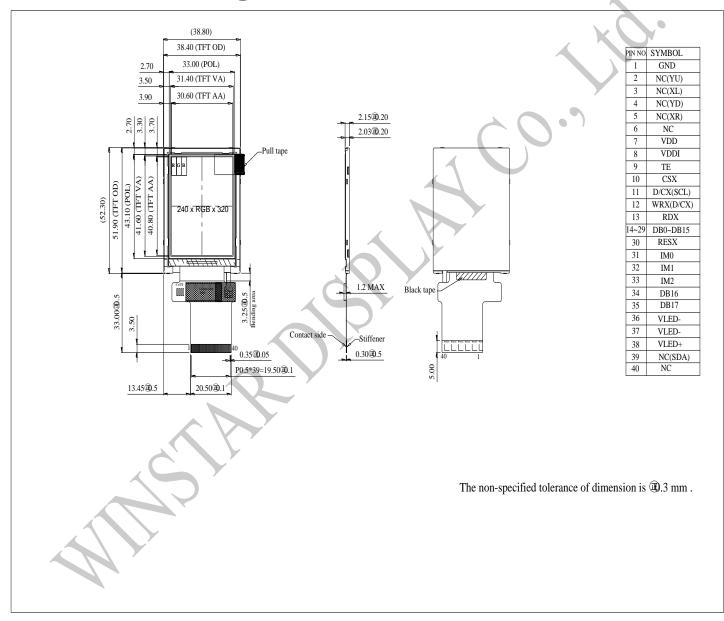
Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

Note4: Some performance degradation allowed. Need Power off self-recoverable. No hardware failure

12.Contour Drawing



13.Initial Code For Reference

```
void ST7789SV WF0200B(void) for SPI & MCU mode
    Write_Command(0x11); //Sleep out
    delay(150);
                            //Delay 120ms
  Write_Command(0x36);
                            //
  Write_Data(0x00);
    Write Command(0x3A); //
  Write_Data(0x55);
    //ST7789S Frame rate setting
    Write Command(0xb2); //Porch Setting
    Write Data(0x0c);
    Write_Data(0x0c);
    Write_Data(0x00);
    Write Data(0x33);
    Write_Data(0x33);
    Write_Command(0xb7);
                           //Gate Control
    //Write_Data(0x35);
                            //vgh vgl
    Write Data(0x64);
    //ST7789S Power setting
                            //Gate Control VCOMS=1.425V
    Write Command(0xbb);
    Write_Data(0x30);
    Write Command(0xc0);
                            //LCM Control
    Write_Data(0x2c);
    Write_Command(0xc2); //VDV and VRH Command Enable
    Write_Data(0x01);
    Write_Command(0xc3);
                            //VRH Set (AVDD=VRH+1.675
    Write Data(0x0b);
    Write_Command(0xc4);
                            //VRH Set
    Write_Data(0x20);
    Write_Command(0xc6);
                            //Frame Rate Control in Normal Mode
    Write Data(0x0f);
    Write Command(0xca);
                           //Register Value Selection 2
    Write_Data(0x0f);
    Write_Command(0xc8);
                           //Register Value Selection 1
    Write Data(0x08);
    Write Command(0x55); //Write Content Adaptive Brightness Control and Color Enhancement
    Write_Data(0x90);
    Write_Command(0xd0); //Power Control
    Write Data(0xa4);
    Write_Data(0xa1);
    Write_Command(0x35); //
    Write_Command(0x26); //Set Gamma
    Write_Data(0x02);
    //ST7789S gamma setting
    Write Command(0xe0);
```

```
Write Data(0xd0);
  Write Data(0x00);
  Write_Data(0x02);
  Write_Data(0x07);
  Write Data(0x0b);
  Write_Data(0x1a);
  Write_Data(0x31);
  Write_Data(0x54);
  Write_Data(0x40);
  Write_Data(0x29);
  Write_Data(0x12);
  Write_Data(0x12);
  Write_Data(0x12);
  Write Data(0x17);
  Write_Command(0xe1);
  Write_Data(0xd0);
  Write_Data(0x00);
  Write_Data(0x02);
  Write_Data(0x07);
  Write_Data(0x05);
  Write_Data(0x25);
  Write_Data(0x2d);
  Write_Data(0x44);
  Write Data(0x45);
  Write_Data(0x1c);
  Write_Data(0x18);
  Write_Data(0x16);
  Write_Data(0x1c);
  Write_Data(0x1d);
Write_Command(0x21);
  Write_Command(0x2A);
  Write_Data(0x00);
  Write_Data(0x00);
  Write Data(0x00);
  Write_Data(0xEF);
  Write Command(0x2B);
  Write_Data(0x00);
  Write_Data(0x0);
 Write_Data(0x01);
  Write_Data(0x3F);
  Write_Command(0x29);
```

}



LCM Sample Estimate Feedback Sheet

Module Number :			Page: 1
1 · Panel Specification :			
1. Panel Type:	□ Pass	□ NG ,	
2. View Direction:	□ Pass	□ NG ,	
3. Numbers of Dots:	□ Pass	□ NG ,	_
4. View Area:	□ Pass	□ NG ,	
5. Active Area:	□ Pass	□ NG ,	
6. Operating	□ Pass	□ NG ,	X V
7. Storage Temperature	: □ Pass	□ NG ,	
8. Others :			
2 · <u>Mechanical</u>		\sim \sim	• •
1. PCB Size:	□ Pass	□ NG ,	
2. Frame Size:	□ Pass	□ NG ,	
3. Material of Frame:	□ Pass	□ NG ,	
4. Connector Position:	□ Pass	□ NG ,	
5. Fix Hole Position:	□ Pass	□ NG ,	
6. Backlight Position:	□ Pass	□ NG ,	_
7. Thickness of PCB:	□ Pass	□ NG ,	
8. Height of Frame to	□ Pass	□ NG ,	
9. Height of Module:	□ Pass	□ NG ,	
10. Others:	□ Pass	□ NG ,	
3 · Relative Hole Size :			
1. Pitch of Connector:	□ Pass	□ NG ,	_
2. Hole size of Connector	r: □ Pass	□ NG ,	
3. Mounting Hole size:	□ Pass	□ NG ,	
4. Mounting Hole Type:	□ Pass	□ NG ,	
5. Others:	□ Pass	□ NG ,	
4 · Backlight Specification	<u>.</u> :		
1. B/L Type:	□ Pass	□ NG ,	
2. B/L Color:	□ Pass	□ NG ,	
3. B/L Driving Voltage (Re	ference for LE		
4. B/L Driving Current:	□ Pass	□ NG ,	
5. Brightness of B/L:	□ Pass	□ NG ,	
6. B/L Solder Method:	□ Pass	□ NG ,	
7. Others:	□ Pass	□ NG ,	

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5 、	Electronic Characteristics	of Module:	
1.	Input Voltage:	□ Pass	□ NG ,
2.	Supply Current:	□ Pass	□ NG ,
3.	Driving Voltage for LCD:	□ Pass	□ NG ,
4.	Contrast for LCD:	□ Pass	□ NG ,
5.	B/L Driving Method:	□ Pass	□ NG ,
6.	Negative Voltage Output:	□ Pass	□ NG ,
7.	Interface Function:	□ Pass	□ NG ,
8.	LCD Uniformity:	□ Pass	□ NG ,
9.	ESD test:	□ Pass	□ NG ,
10.	Others:	□ Pass	□ NG ,
6、	Summary :		
	signature:	^	Date: / /